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(74) Agent: **BARTH, Stephan**; Reinhard, Skuhra, Weise & Partner, Friedrichstrasse 31, 80801 München (DE).

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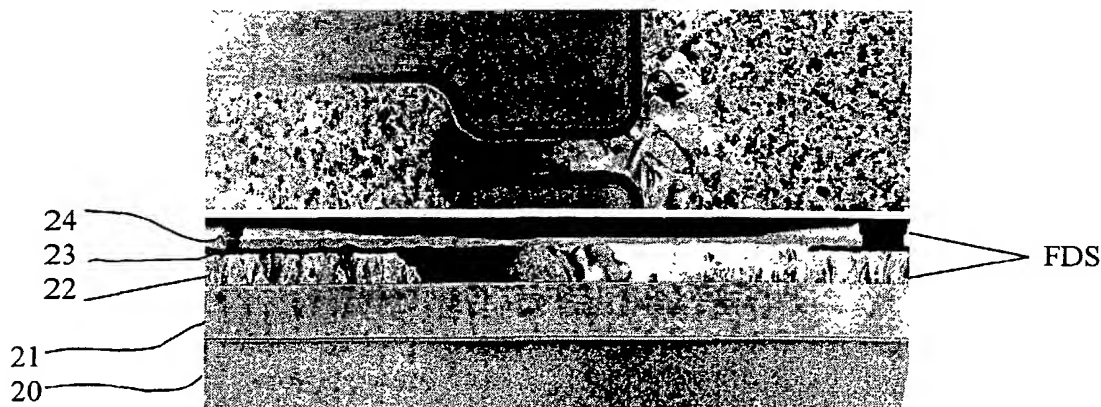
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(71) Applicant: **INFINEON TECHNOLOGIES AG**
[DE/DE]; St.-Martin-Strasse 53, 81669 München (DE).

(72) Inventor: **KOTHANDARAMAN, Chandrasekharan**;
19 E. Surry Lane, Wappingers Falls, NY 12590 (US).

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(54) Title: OPTICALLY AND ELECTRICALLY PROGRAMMABLE SILICIDED POLYSILICON FUSE DEVICE



(57) Abstract: A silicided polysilicon based fuse device that is programmable by optical and electrical energy in the polysilicon layer without damage to nearby structures, comprising: a Si substrate; an insulating layer disposed on the substrate; and a fuse device section comprising poly-Si/a silicide/ and a barrier layer, the fuse device section forming an electrical discontinuity in the poly Si layer in response to an electrical pulse or an optical pulse applied to it.



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Optically and electrically programmable silicided Polysilicon
Fuse Device

5 Specification

1. Field of Invention

The invention relates to integrated circuit devices, and more
10 particularly, to fusible link devices in semiconductor
integrated circuits in which the laser fuse is made in the
poly-Si level, as opposed to the metal level, which can be
placed in oxide.

15 2. The Prior Art

In general, today, integrated circuits are made with internal
connections that are set during manufacturing; however, due to
high development costs, lengthy lead times, and the high
20 tooling costs of these circuits, the end user prefers circuits
which can be programmed in the field. These circuits are
typically referred to as programmable circuits since they
usually contain programmable links.

25 Programmable links are electrical interconnects which are
broken or created at selected electronic nodes by the end user
after the integrated circuit device has been fabricated in
order to activate or deactivate the selected electronic nodes.
As a case in point, programmable links are used widely in
30 programmable read-only memory devices (PROMs). In this
connection, it is pointed out that the most common form of

programmable link is the fusible link. Upon obtaining a PROM device, typically it will consist of an X-Y lattice of conductors or semiconductors. The lattice comprises a cross-over point of a conducting link, which is referred to as a fusible link, that connects a transistor to this lattice network. To program the PROM, the fusible link is blown at selected nodes to create an open circuit. The combination of blown and unblown links constitutes a digital bit pattern of ones and zeros that constitute data which the user stores in the PROM.

Some of the key disadvantages of fusible link PROM systems is that, because of the nature of the conducting material in the link, high voltage and high current levels are usually needed during programming in order to complete blowing of the fusible link. Because the link is relatively high in conductance, it requires a considerable amount of power dissipation to blow it.

Further, the size and shape of the fusible link must be exacting so that the link will function effectively as a conductor if it is not blown and be a completely open circuit if it is blown.

A second type of programmable link has also been utilized frequently. The second type of programmable link is referred to as an anti-fuse link, and enjoys considerable use in integrated circuit applications. In the anti-fuse link, instead of the programming mechanism causing an open circuit as is the case with fusible links, the programming mechanism creates a short circuit or low resistance link. The anti-fuse link consists of two conductor and/or semiconductor materials with a dielectric

or insulating material between them. During programming, the insulating or dielectric material at selected points in between the conductive material is broken down by a predetermined applied voltage to electrically connect the conducting or semiconducting materials together.

A silicide agglomeration fuse device is disclosed in U.S. Patent 5,708,291. The fusible link device is disposed on a semiconductor substrate and comprises:

a polysilicon layer having a first resistance;

a silicide layer formed on the polysilicon layer, the silicide layer having a second resistance lower than the first resistance, the silicide layer agglomerating to form an electrical discontinuity in response to a predetermined programming potential being applied across the silicide layer, such that the resistance of the fusible link device can be selectively increased and;

nine contacts electrically coupled to either end of the silicide layer for receiving the programming potential.

U.S. Patent 5,969,404 disclose a fusible link device on a semiconductor substrate for providing discretionary electrical connections. The fusible link device has a first un-programmed resistance and includes a polysilicon layer and a silicide layer. The silicide layer is formed on the polysilicon layer, and agglomerates to form an electrical discontinuity in response to a predetermined programming potential being applied across the silicide layer, such that the resistance of the

fusible link device can be selectively increased to a second programmed resistance.

A polysilicon fuse array structure for integrated circuits is disclosed in U.S. Patent 5,536,968. The semiconductor structure comprises:

a first electrical conductor;

10 a second electrical conductor electrically separated from the first electrical conductor;

a polysilicon strip connecting the first and second electrical conductors and forming a fuse between the first and second electrical conductors, the polysilicon strip including a narrow middle section, whereby the fuse will be opened by a current which is passed from the first electrical conductor through the polysilicon strip into the second electrical conductor;

20 a first patterned signal layer, the first electrical conductor and the polysilicon strip residing in the first patterned signal layer; and

25 a second patterned signal layer electrically separated from the first patterned signal layer, the second electrical conductor residing in the second patterned signal layer.

30 U.S. Patent 6,104,079 disclose closely pitched polysilicon fuses and a method for making the same. In the method for

decreasing the pitch of polysilicon fuses tungsten barriers are formed adjacent to the fuse elements and the tungsten barriers are made compatible with the process to form a crack stop. The tungsten is stacked at the via level on top of the tungsten at the contact level in the crack stop, and the interlevel dielectric is used as a cover for the fuse. In this way, the tungsten fuse barrier process is made compatible with the polysilicon fuse crack stop process.

10 An electrically global fuse in a reduced co-sectional area is disclosed in U.S. Patent 6,222,244 B1. The semiconductor fuse is positioned between conductors for connecting at least two wiring lines. The fuse comprises spacers positioned on adjacent one's of the conductors, and the fuse element is positioned
15 between the spacers and connected to the wiring lines. A space between the conductors comprises the first width comprising a smallest possible photolithographic width and the fuse element has a second width smaller than the first width. This fuse protects the semiconductor device from excessive voltage and/or
20 current or selectively and permanently connect/disconnect semiconductor devices from one another.

U.S. Patent 5,266,829 disclose an electrically programmable low-impedance, anti-fuse element. It consists of a capacitor-like structure having a first electrode and a second electrode
25 with a dielectric layer in between, characterized by a high impedance and very low leakage current before programming and a low-resistance after programming. A plurality of these anti-fuses is disposed in a semiconductor integrated circuit, and
30 maybe selectively blown to create low impedance interconnects at selected locations within the integrated circuit. The anti-

fuses may be blown either before or after packaging of the integrated circuit die.

U.S. Patent 5,882,998 disclose a low power programmable fuse
5 structure and method of making the same. The method comprises:

providing a substrate having a filed oxide region;

10 forming a mask over the doped polysilicon strip such that
a window exposing the doped polysilicon strip is defined
at about the center of the doped polysilicon strip;

15 applying an increased implant dose over the mask and the
exposed doped polysilicon strip lying within the window to
produce an increased dopant concentration region in the
doped polysilicon strip, the increased implant dose being
between about $3 \cdot 10^{15} \text{ cm}^{-2}$ and about $6 \times 10^{15} \text{ atoms cm}^{-2}$; and

20 forming a silicide metal over the doped polysilicon strip
such that a thinner layer of the silicide metal is formed
over the increased dopant concentration region and a
thicker layer of the silicide metal is formed over other
regions of the doped polysilicon strip.

25 There is a need in the art of utilizing programmable fuses in
integrated circuits to reduce the damage to SILK by other than
the current method of using fuses in the final metal level
which may be placed in oxide, and wherein some damage to the
structure still results.

There is a further need in the art of providing programmable fuse links for use in integrated circuits to alleviate physical damage to the structure, as is typically the case when the fuses are electrically programmed.

5

There is a further need in the art of providing programmable fuses for use in integrated circuits to be able to utilize less energy when compared to ablation or melting, and to reduce the pitch and damage to nearby structures.

10

Finally, there is a need in the art of providing programmable fuses for use in integrated circuits to eliminate refractory metals that are normally needed as liners for poly-Si lines, to be able to use shorter wavelengths, and thereby tighter focal spots that lead to reduced pitch, but which also lends itself to being electrically programmed (and thereby provide the improved flexibility of affecting programming with either optical energy or electrical energy).

15

20 3. Summary of the Invention

One object of the present invention is to provide programmable fuses in integrated circuits that reduce the damage to interlevel dielectrics and neighboring structures by avoiding using fuses in the final metal level (which may be placed in oxide), and where some damage to the structure still occurs.

25

Another object of the present invention is to provide programmable fuse links for use in integrated circuits that, unlike all currently known methods of programming, are free from physical damage to the structure.

30

A further object of the present invention is to provide programmable fuses for use in integrated circuits that utilize less energy in comparison to ablation or melting techniques, and that reduces the pitch and damage to nearby structures upon programming.

A yet further object of the present invention is to provide programmable fuses for use in integrated circuits that are capable of being programmed by optical means, of shorter wavelengths, and thereby reducing the focal spot size of the optical beam that lead to reduced pitch, but which also lends itself to being electrically programmed as well as optically programmed.

4. Brief Description of the Drawing Figures

Fig. 1 is a microphotograph of a fuse link of the prior art in which there are metal lines on oxide/low dielectric constant materials, and in which there is a splatter.

Fig. 2 is a microphotograph of a fuse link of the prior art in which there is a metal line on oxide/low-dielectric constant materials, and in which there is a crack.

Fig. 3 is a microphotograph of the silicided polysilicon based fuse of the invention after programming.

Fig. 4 shows a top view of a microphotograph of a fusible link device of the present invention comprising a large array

structure of an eFuse bank in which silicided poly-Si lines are programmed by a thick-oxide.

Fig. 5 shows a top view of a microphotograph of a single fusible link device of the present invention comprising an eFuse in which silicided Poly-Si lines are programmed by a thick-oxide.

5. Detailed Description of preferred Embodiment of the Inventor

Reference is now made to Fig. 1 which shows a microphotograph of a fuse link, wherein metal lines on oxide/low dielectric constant materials evidence a splatter formed by the high energy needed to program this fuse. When programming similar fuse links found in the prior art, a large pitch is needed and this is another disadvantage attendant to the use of this fuse link. Further disadvantages associated with the large pitch that is needed for programming in the prior art fuse link is the damage caused to the layers beneath the fuse, and that the fuses are isolated in a fuse box (and this causes an area penalty). Additionally, there are complications in back-end integration - such as flip chip bonding - when utilizing this prior art poly-Si based fuse link.

A still further disadvantage in addition to the splatter created from high energy when programming the prior art fuse link is that cracks are created upon programming, as can be seen in the microphotograph of Fig. 2.

The invention silicided polysilicon based fuse device that may be programmed either optically or electrically is shown in Fig. 3. In this figure, which comprises a top view as well as a cross sectional side view of the silicided polysilicon based fuse device, there is a silicon substrate 20 with an insulating layer 21 disposed above. In this embodiment of the fuse device, the fuse device section FDS is disposed on the insulating layer 21, as a part of a larger integrated circuit device. The polysilicon layer 22 may be doped p-type; however, other embodiments or configurations may include other types of doping including n-type or the formation of p-n junctions in the polysilicon layer 22. The fuse device section FDS includes a Cobalt silicide (CoSi_2) layer 23 disposed on the polysilicon layer 22, and a transparent passivation layer 24 on the CoSi_2 layer 23. In operation, the fuse device section FDS is characterized by a resistance in the silicided polysilicon before it is programmed or blown. As may be seen from Fig. 3, in the programmed state, the higher resistance is obtained because of the removal of the CoSi_2 in some regions. It is apparent that the fuse link has not been physically ruptured in order to achieve this higher resistance state. Furthermore, the passivation layer 24 is unperturbed during the entire process.

It is believed that any dopants in the polysilicon that may contribute to any residual conduction have also rendered inactive due to programming. The SiN layer functions as an encapsulation or barrier layer, which while allowing the transmission of optical energy, allows for the change in the resistance of the silicided polysilicon layer without rupturing this layer.

In the context of the invention, while CoSi_2 is preferred as the silicide, other silicides such as titanium, tungsten, or platinum silicides are equally operable. Also, in the context of the invention the SiN is the preferred encapsulation layer; however, any transparent, encapsulation or barrier layer will suffice.

Fig. 4 shows a microphotograph of the present invention structure comprising a large array of fuse links, showing silicided poly-Si links that are programmed. Preferably, the programming in this embodiment is done at about 3.3V and about 10mA for about 200 microseconds, whereupon current is caused to flow between contacts 30 as shown in Fig. 5. The current flows through the fuse link to affect a change in the resistance of the fuse link, without rupturing the link 31. In other words, the basic resistivity fuse link is changed. The silicided polysilicon based fuse device of the invention may be programmed by the application of optical energy in the visible and NIR (near infrared) range realizing the increased local resistivity, again without any rupture. Further, there is no absorption in the inter-level dielectrics, oxide and nitride.

The novel inventive structure removes the disadvantages of metal-link laser fuses, provides flexibility in product choice and test flow, and allows programming by either laser or electrical means, and in so doing, induces a large resistance change in excess of 10^5 Ohms, without rupture of the link.

Claims

1. A silicided polysilicon based fuse device that is
programmable by optical and electrical energy in the
5 polysilicon layer without damage to nearby structures,
comprising:

a Si substrate;

10 an insulating layer disposed on said substrate; and

a fuse device section comprising poly Si/a silicide/and a
barrier layer, said fuse device section showing a local
increase in its resistance due to the application of an
15 electrical pulse applied across it or by the application
of an optical beam over it.

2. The silicided polysilicon based fuse device of claim 1
wherein said barrier layer is SiN.

20

3. The silicided polysilicon based fuse device of claim 1
wherein said insulating layer silicon dioxide.

4. The silicided polysilicon based fuse device of claim 3
25 wherein said insulating layer is silicon nitride.

5. The silicided polysilicon based fuse device of claim 1
wherein said silicide is selected from the group consisting
of cobalt silicide, titanium silicide, tantalum silicide and
30 platinum silicide.

6. The silicided polysilicon based fuse device of claim 3,
wherein said silicide is cobalt silicide.
7. The silicided polysilicon based fuse device of claim 3
5 wherein said silicide is titanium silicide.
8. The silicided polysilicon based fuse device of claim 3
wherein said silicide is tungsten silicide.
- 10 9. The silicided polysilicon based fuse device of claim 3,
wherein said silicide is tantalum silicide.
10. The silicided polysilicon based fuse device of claim 3,
wherein said silicide is platinum silicide.
15
11. The silicided polysilicon based fuse device of claim 2,
wherein said silicide is selected from the group consisting
of cobalt silicide, titanium silicide, tungsten silicide,
titanium silicide and platinum silicide.
20
12. The silicided polysilicon based fuse device of claim 11,
wherein said silicide is cobalt silicide.
13. The silicided polysilicon based fuse device of claim 11,
25 wherein said silicide is titanium silicide.
14. The silicided polysilicon based fuse device of claim 11,
wherein said silicide is tungsten silicide.
- 30 15. The silicided polysilicon based fuse device of claim 11,
wherein said silicide is tantalum silicide.

16. The silicided polysilicon based fuse device of claim 11,
wherein said silicide is platinum silicide

5 17. The silicided polysilicon based fuse device of claim 11,
wherein the programming potential is about 3.3V.

18. The silicided polysilicon based fuse device of claim 11,
wherein the programming is by an optical beam.

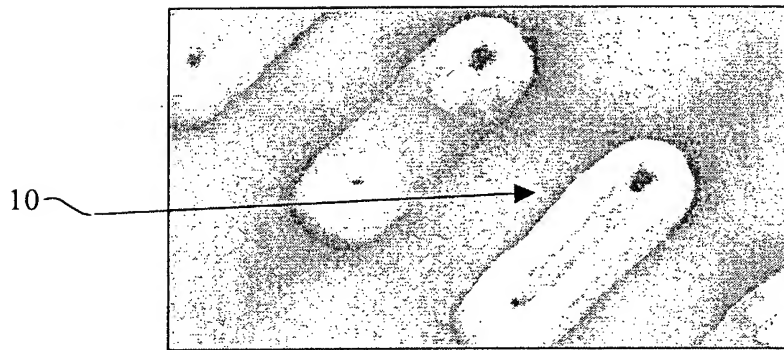


FIG. 1

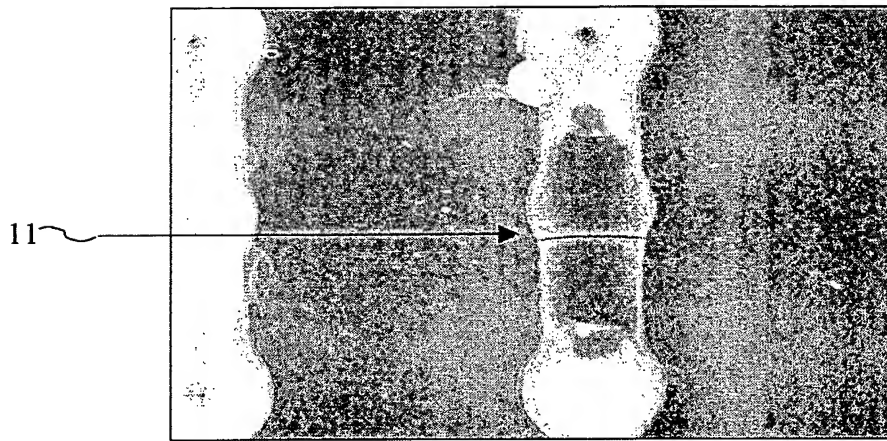


FIG. 2

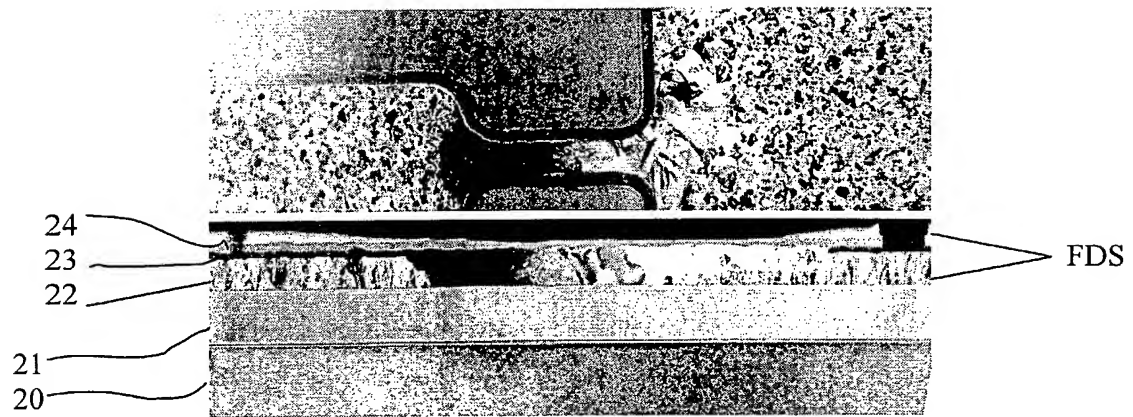


FIG. 3

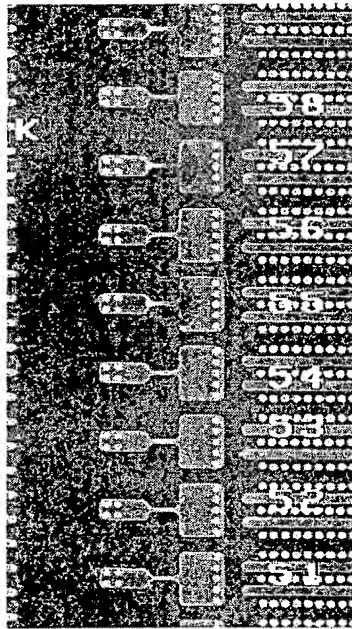


FIG. 4

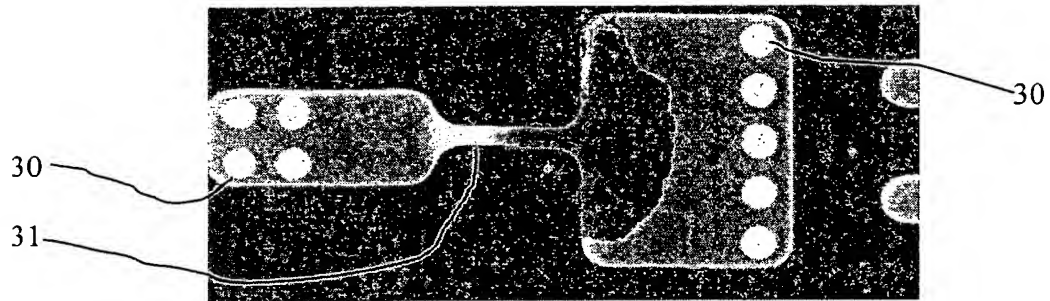


FIG. 5

INTERNATIONAL SEARCH REPORT

International Application No

PCT/EP 02/08647

A. CLASSIFICATION OF SUBJECT MATTER

IPC 7 H01L23/525

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC 7 H01L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	EP 0 999 592 A (SIEMENS AG) 10 May 2000 (2000-05-10) column 1, line 38 - line 57 column 2, line 8 - line 14 figure 1	1-18
A	US 5 969 404 A (BOHR MARK T ET AL) 19 October 1999 (1999-10-19) cited in the application figures 1,2	1-18



Further documents are listed in the continuation of box C.



Patent family members are listed in annex.

* Special categories of cited documents :

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X document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

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Date of the actual completion of the international search

27 December 2002

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08/01/2003

Name and mailing address of the ISA

European Patent Office, P.B. 5818 Patentlaan 2
NL - 2280 HV Rijswijk
Tel. (+31-70) 340-2040, Tx. 31 651 epo nl,
Fax: (+31-70) 340-3016

Authorized officer

Munnix, S

INTERNATIONAL SEARCH REPORT

Information on patent family members

International Application No

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